nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

| Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test | | User Part Number PMEG6020EXE-Q | | | | | | | | | | | | |
|--|-----------------------------|--|-----------------|--------------|-------|-----------|-----------|-----------|----------------------|--|--|--|--|--|
| | | | | | | | | | Part Description | | | | | |
| | | Nexperia DHAM Schottky SMD package Test Conditions Duration # Lots # Quantity # Reject | | | | | | | | | | | | |
| | | | | | | | | | TEST | | | | | |
| | | | | | | | | | Pre- and Post-Stress | | | | | |
| | | # E1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | | | | | |
| | | JESD22-A113 | ., | | | | | | | | | | | |
| | | Bake Tamb = $125 ^{\circ}\text{C}$ | 24 hours | | | | | | | | | | | |
| | PC | Soak Tamb = 85 °C, RH = 85% | 168 hours | | | | | | | | | | | |
| # A1 | Preconditioning | Reflow soldering | 3 cycles | 1514 | 64430 | 0 | | | | | | | | |
| | | MIL-STD-750-1 | - | | | | | | | | | | | |
| | HTRB | M1038 Method A | | | | | | | | | | | | |
| | High Temperature Reverse | Tj = Tjmax, Vr = 100% of max. datasheet | | | | | | | | | | | | |
| # B1 | Bias | reverse voltage ^[1] | 1000 hours | 206 | 9320 | 0 | | | | | | | | |
| | | | | | | | | | | | | | | |
| | тс | JESD22-A104 | | | | | | | | | | | | |
| # A4 | Temperature Cycling | -65 °C to Tjmax, not to exceed 150°C | 1000 cycles | 311 | 14080 | 0 | | | | | | | | |
| | | | | | | | | | | | | | | |
| | UHAST | JESD22-A118 | | | | | | | | | | | | |
| # A3 or | Unbiased HAST | Tamb = 130 °C, RH = 85 % | 96 hours | 311 | 14080 | 0 | | | | | | | | |
| | | JESD22-A102 | | | | | | | | | | | | |
| | AC | Tamb = $121 ^{\circ}C$, RH = $100 ^{\circ}M$ | | | | | | | | | | | | |
| # A3 alt | Autoclave | Pressure = $205 \text{ kPa} (29.7 \text{ psia})$ | | | | | | | | | | | | |
| | | | | | | | | | | | | | | |
| | H3TRB | JESD22-A101 | | | | | | | | | | | | |
| | High Humidity High | Tamb = 85 °C, RH = 85%, VR = 80 % of | | | | | | | | | | | | |
| # A2 alt | Temperature Reverse Bias | rated reverse voltage ^{[1], [2]} | 1000 hours | 311 | 14080 | 0 | | | | | | | | |
| # 712 UIC | | MIL-STD-750 Method 1037 | | | | | | | | | | | | |
| | IOL | ton = toff, devices powered to insure ΔT_j = | | | | | | | | | | | | |
| # A5 | Intermittent Operating Life | | 1000 hours | 312 | 14120 | 0 | | | | | | | | |
| | | | | 3.2 | | - | | | | | | | | |
| | RSH | JESD22-A111 | | | | | | | | | | | | |
| # C8 | Resistance to Solder Heat | 260 °C ± 5 °C | 10 s | 269 | 8070 | 0 | | | | | | | | |
| | SD | | | 200 | 2070 | - | | | | | | | | |
| # C10 | Solderability | J-STD-002 | | 222 | 6660 | 0 | | | | | | | | |
| | , | des have to be considered (thermal runaway). | | | | ~ | | | | | | | | |

The physical limitations of Schottky diodes have to be considered (thermal runaway).
The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia | | | | | |
| DHAM | Schottky | 9320 | 0 | 0,46 | 2,19E+09 |

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